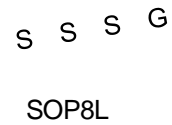


P-Channel Enhancement Mode MOSFET

Feature

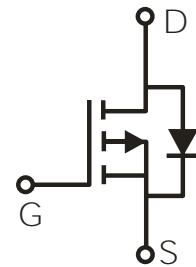
- -40V/-10A
 $R_{DS(ON)} = 11.3\text{ m}\Omega(\text{typ.}) @V_{GS} = -10V$
 $R_{DS(ON)} = 16.1\text{ m}\Omega(\text{typ.}) @V_{GS} = -4.5V$
- 100% Avalanche Tested
- Reliable and Rugged
- Halogen Free and Green Devices Available
 (RoHS Compliant)

Pin Description



Applications

- Switching application
- Li-battery protection
- DC-DC
- Motor control



Single P-Channel MOSFET

Ordering and Marking Information

 S HYG120P04 XYMXXXXXX	Package Code S:SOP8L Date Code XYMXXXXXX
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Note: HUAYI halogen free products contain molding compounds/die attach materials and 100% matte tin plate Termination finish; which are fully compliant with RoHS. HUAYI halogen free products meet or exceed the halogen free requirements of IPC/JEDEC J-STD-020 for MSL classification at halogen free peak reflow temperature. HUAYI defines "Green" to mean halogen free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

HUAYI reserves the right to make changes, corrections, enhancements, modifications, and improvements to this product and/or to this document at any time without notice.

Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit	
Common Ratings (Tc=25°C Unless Otherwise Noted)				
V _{DSS}	Drain-Source Voltage	-40	V	
V _{GSS}	Gate-Source Voltage	±20	V	
T _J	Junction Temperature Range	-55 to 175	°C	
T _{STG}	Storage Temperature Range		°C	
I _S	Source Current-Continuous(Body Diode)	Tc=25°C	-10	A
Mounted on Large Heat Sink				
I _{DM}	Pulsed Drain Current *	Tc=25°C	-30	A
I _D	Continuous Drain Current	Tc=25°C	-10	A
		Tc=100°C	-7	A
P _D	Maximum Power Dissipation	Tc=25°C	3	W
		Tc=100°C	1.5	W
R _{JA}	Thermal Resistance, Junction-to-Ambient **		50	°C/W
E _{AS}	Single Pulsed-Avalanche Energy ***	L=0.3mH	107	mJ

Note: * Repetitive rating; pulse width limited by max.junction temperature.
 ** Surface mounted on 1in2 FR-4 board.
 *** Limited by T_{Jmax} , starting T_J=25°C, L = 0.3mH, R_G= 25 , V_{GS} =-10V.

Electrical Characteristics(Tc =25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	HYG120P04LQ1			Unit
			Min	Typ.	Max	
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =-250μA	-40	-	-	V

Electrical Characteristics (Cont.) (Tc =25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	HYG120P04LQ1			Unit
			Min	Typ.	Max	
Dynamic Characteristics						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, F=500KHz	-	6.3	-	
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-25V, Frequency=500KHz	-	1794	-	pF

Typical Operating Characteristics

Figure 1: Power Dissipation

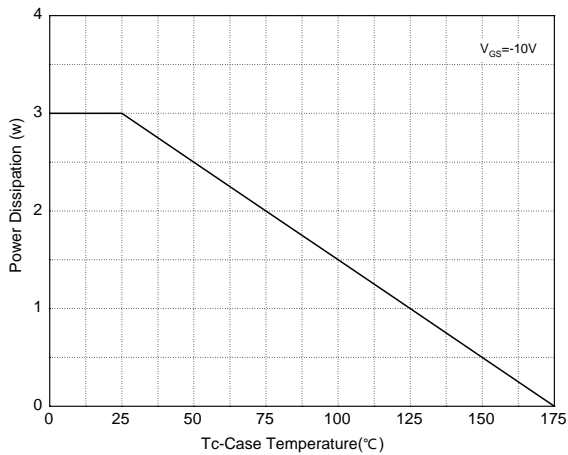


Figure 3: Safe Operation Area

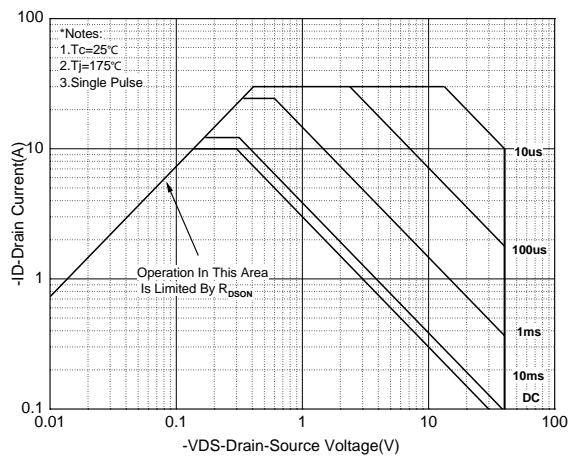


Figure 5: Output Characteristics

Figure 2: Drain Current

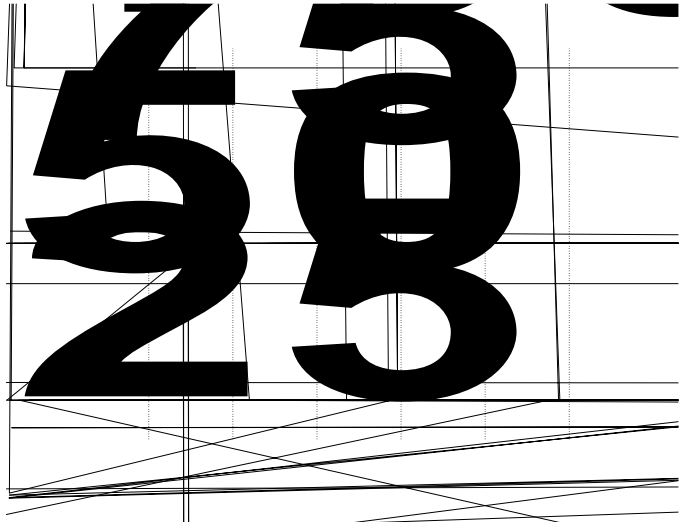


Figure 4: Thermal Transient Impedance

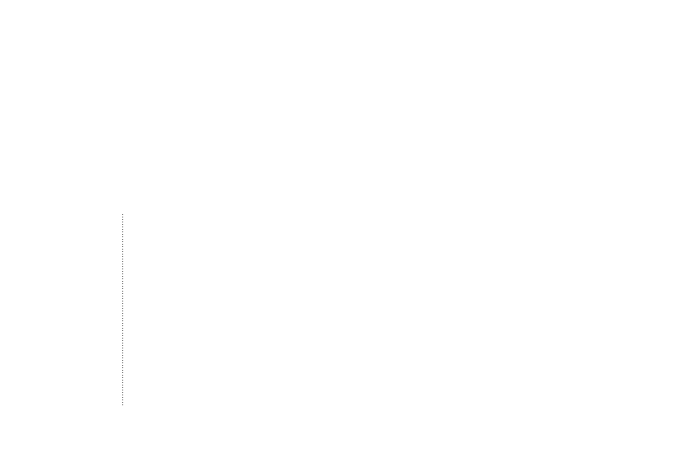


Figure 6: Drain-Source On Resistance

Typical Operating Characteristics(Cont.)

Figure 7: On-Resistance vs. Temperature

Figure 8: Source-Drain Diode Forward

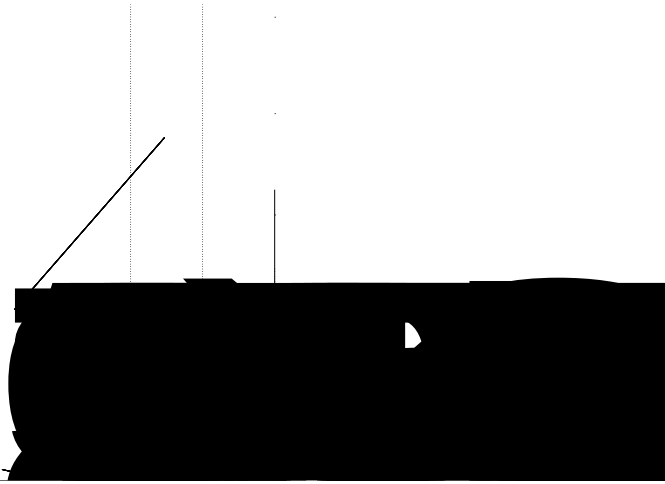
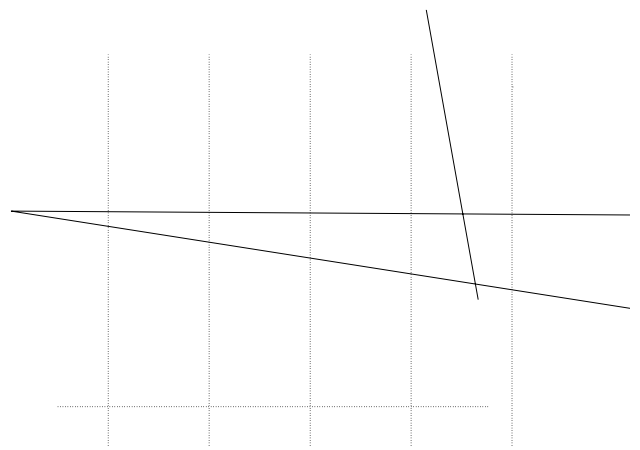
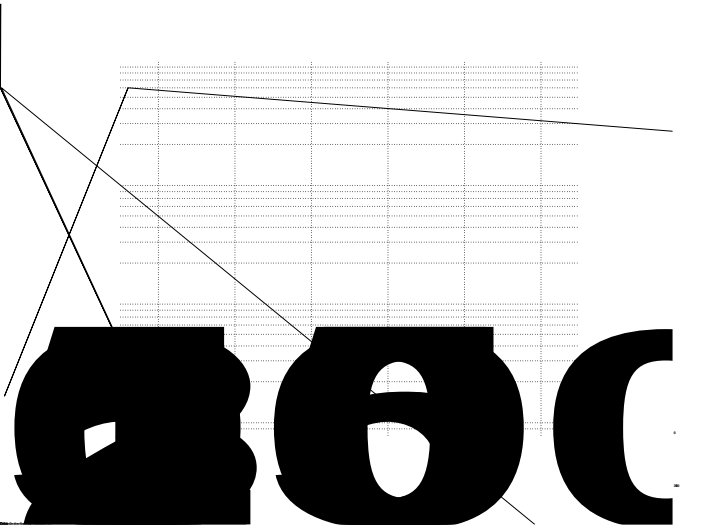
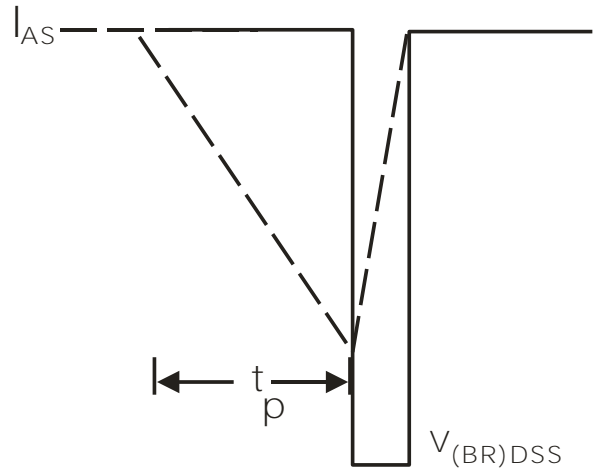


Figure 9: Capacitance Characteristics

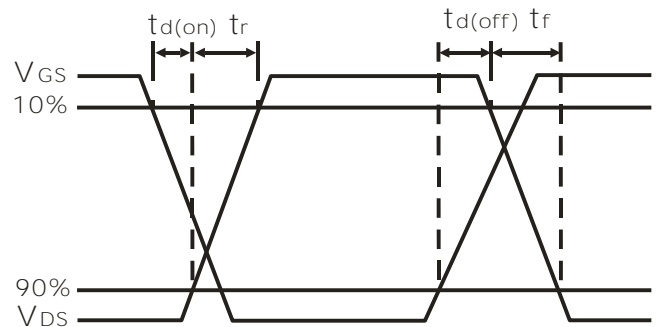
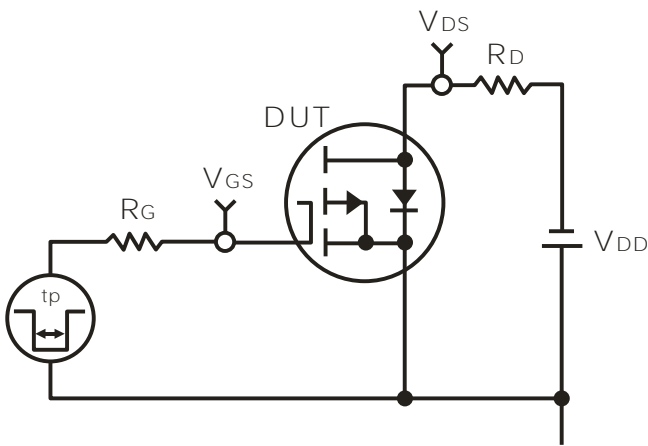
Figure 10: Gate Charge Characteristics



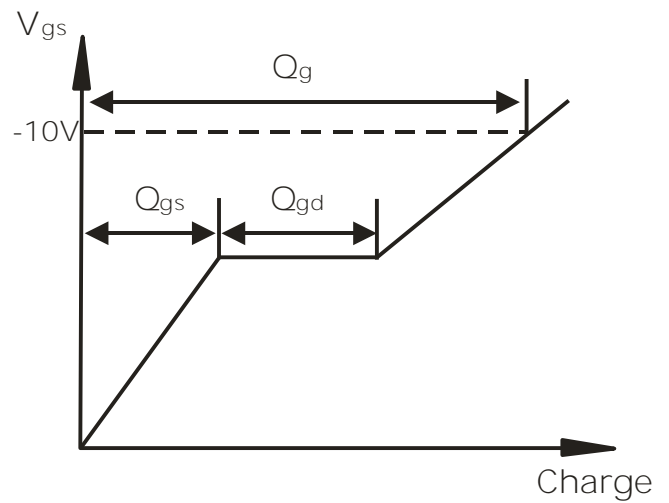
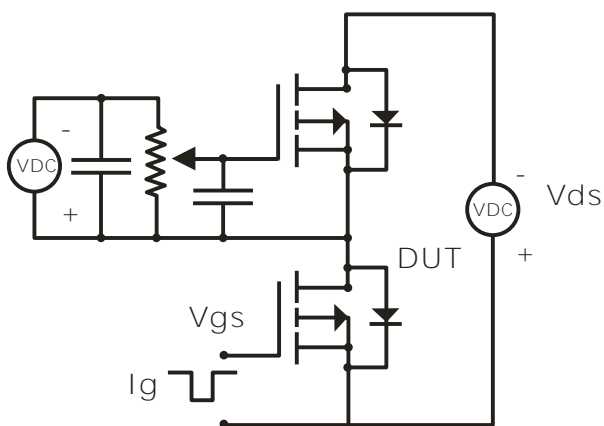
Avalanche Test Circuit



Switching Time Test Circuit



Gate Charge Test Circuit



Device Per Unit

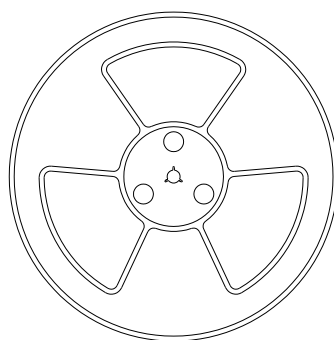
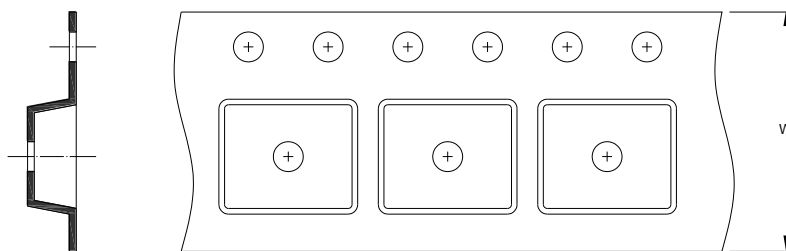
Package Type	Unit	Quantity
SOP8L	Reel	2500

Package Information

Note:

1. Follow JEDEC MS-012AA.
2. Dimension D" does not include mold flash, protrusions or gate burrs.
Mold flash, protrusion or gate burrs shall not exceed 6 mil per side.
3. Dimension E" does not include inter-lead flash or protrusions.
Inter-

Carrier Tape & Reel Dimensions



Application	A	H	T1	C	d	D	W	E1	F
SOP8L	330 2.00	50 MIN	12.4+2.00 -0.20	13.0+0.50 -0.20	1.5 MIN	20.2 MIN	12.0 0.30	1.75 0.10	5.5 0.05
	P0	P1	P2	D0	D1	T	A0	B0	K0
	4.0 0.10	8.0 0.10	2.0 0.05	1.5+0.10 -0.00	1.5 MIN	0.6+0.00 -0.40	6.40 0.20	5.20 0.20	2.10 0.20

Taping Direction Information

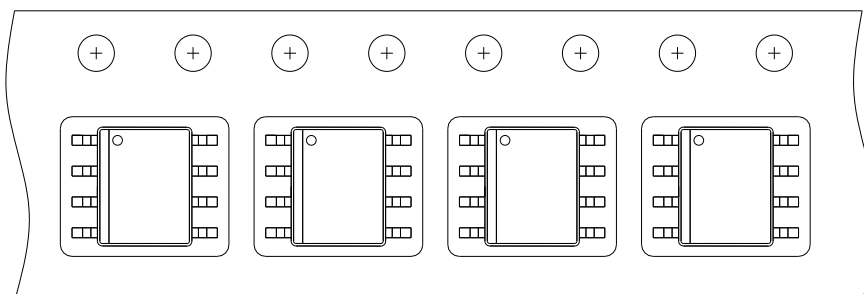
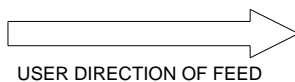


Table 1.SnPb Eutectic Process – Classification Temperatures (Tc)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2.Pb-free Process – Classification Temperatures (Tc)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ ≥2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HTRB	JESD-22, A108	168/500 Hrs, Bias @ 150°C
HTGB	JESD-22, A108	168 /500 Hrs, V _{gs} 100% @ 150°C
PCT	JESD-22, A102	96 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	250/500 Cycles, -55°C~150°C

Customer Service

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Technical Support: Technology@hymexa.com

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